Infrared Repairing ASIC VGA Automatic Welding Machine WDS-620 wisdomshow SMD Rework Station Automatic Optical Alignment System

Our Product Introduction

Basic Information

Place of Origin:	CHINA
Brand Name:	WDS
Certification:	CE
Model Number:	WDS620
Minimum Order Quantity:	1
Packaging Details:	wooden case
Delivery Time:	3-5days
Payment Terms:	TT
Supply Ability:	200

Product Specification

Power Supply:	220V/110V
Weight:	55kg
Bga Size:	Max. 80x80mm
Heating Method:	Infrared + Hot Air
Sensor:	2PCS
Power Consumption:	5200W
Maximum Mounting Load:	300g
Pcb Thickness:	0.3-5mm

More Images

Product Description

Product Description:

The Semi Automatic BGA Rework Station is a highly efficient and precise tool designed for the repair and rework of Ball Grid Array (BGA) components on printed circuit boards (PCBs). Combining advanced technology with user-friendly features, this rework station ensures high-quality results in electronic manufacturing and repair processes. Its semi-automatic placement mode offers a perfect balance between manual control and automated precision, making it ideal for technicians who require accuracy without sacrificing flexibility.

One of the standout features of this BGA rework station is its impressive placement accuracy of ±0.01mm. Such precision is critical when dealing with modern electronic components, where even the slightest misalignment can lead to malfunction or reduced performance. The station's optical alignment system further enhances this precision by providing real-time, high-resolution visual feedback during the placement process. This system allows operators to align BGA components with exceptional accuracy, reducing errors and improving overall repair quality.

The station supports a maximum mounting load of up to 300 grams, accommodating a wide range of BGA components used in various electronic devices. This capacity ensures that even relatively large and heavy components can be handled safely and securely during the rework process. Additionally, the station is compatible with PCB thicknesses ranging from 0.3mm to 5mm, making it versatile enough to work with different types of circuit boards commonly found in consumer electronics, telecommunications, automotive electronics, and industrial equipment.

Heating is a critical aspect of BGA rework, and this station excels in that regard by featuring a sophisticated three heating zone design. This configuration includes an upper hot air heater with a maximum power of 1200W, which provides rapid and uniform heating to the component and surrounding PCB area. The three heating zones allow for precise temperature control and distribution, which helps prevent thermal damage to sensitive components and substrates. By delivering consistent and controlled heat, the rework station enhances solder joint quality and reliability after reflow or repair.

The semi-automatic functionality of the station not only improves placement accuracy but also speeds up the overall rework process. Operators can easily control the placement and heating stages with minimal manual intervention, reducing the risk of operator error and fatigue. The intuitive interface and ergonomic design further contribute to ease of use, making the device suitable for both experienced technicians and those new to BGA rework.

In summary, the Semi Automatic BGA Rework Station is an essential tool for any electronics repair or manufacturing environment that demands high precision and reliability. Its advanced optical alignment system ensures exact positioning of components, while the three heating zone setup provides optimal thermal management. With a maximum mounting load of 300g and support for PCB thicknesses between 0.3mm and 5mm, this rework station is versatile enough to handle a broad spectrum of BGA components and PCB types. The powerful upper hot air heater, delivering up to 1200W, guarantees efficient and uniform heating, essential for successful soldering and component replacement.

Overall, this BGA rework station combines precision, power, and practicality, making it an excellent investment for improving repair quality, reducing rework time, and enhancing the longevity of electronic devices. Whether you are working in a small repair shop or a large manufacturing facility, this semi-automatic BGA rework station provides the reliability and performance needed to meet the demands of modern electronics assembly and repair.

Features:

Product Name: Semi Automatic BGA Rework Station
Upper hot air heater power: Max 1200W
Maximum mounting load: 300g
Power consumption: 5200W
Equipped with 2PCS sensors for precise temperature control
Power supply options: 220V/110V
Features three heating zones for efficient and even heating
Ideal for motherboard repair and rework applications
Designed specifically to enhance motherboard repair processes

Technical Parameters:

Upper Hot Air Heater	Max 1200W
Down Hot Air Heater	Max 1200W
Power Consumption	5200W
Maximum Mounting Load	300g
Placement Accuracy	±0.01mm
Heating Method	Infrared + Hot Air
PCB Size	Max. 470x380mm
Power Supply	220V/110V
Weight	55kg
Sensor	2PCS

Applications:

The WDS Semi Automatic BGA Rework Station, model WDS620, is a highly efficient and reliable tool designed for precise and professional CPU repair tasks. Originating from China and certified with CE, this rework station combines advanced technology with user-friendly features, making it ideal for various application occasions and scenarios in electronics repair and manufacturing industries.

One of the primary application occasions for the WDS620 is in the repair and rework of CPUs and other delicate BGA components on printed circuit boards. The station’s powerful heating method, which integrates Infrared preheating table technology with hot air heating, ensures uniform and controlled temperature distribution. This dual heating approach allows technicians to perform CPU repair with minimal risk of damage, as the Infrared preheating table gently warms the board from underneath while the hot air heater, with a maximum power of 1200W, targets the CPU or BGA component directly. This precise temperature control is crucial for successful reflow soldering and component replacement.

The semi-automatic operation of the WDS620 enhances efficiency during repair processes, making it suitable for small to medium-scale production environments as well as specialized repair workshops. Its robust power consumption of 5200W and optimal dimensions (L800xW780xH810mm) provide a stable and spacious working area, accommodating various board sizes and component types. The maximum mounting load of 300g ensures that even relatively heavy components can be handled safely without compromising accuracy.

In addition to CPU repair, the WDS620 is widely used in scenarios such as smartphone motherboard repairs, tablet maintenance, and other electronic device refurbishments where BGA rework is necessary. The product’s packaging in a sturdy wooden case guarantees safe transportation, and with a delivery time of just 3-5 days and a supply ability of 200 units, it is a reliable choice for businesses requiring prompt and consistent equipment availability. Payment terms by TT further facilitate smooth procurement processes.

Overall, the WDS Semi Automatic BGA Rework Station WDS620 is an indispensable tool in the electronics repair field, especially for CPU repair tasks. Its advanced Infrared preheating table combined with hot air heating technology, CE certification, and thoughtful design features make it an excellent investment for professionals seeking quality and efficiency in BGA rework operations.

Customization:

The WDS Semi Automatic BGA Rework Station, model WDS620, is designed to meet all your motherboard repair needs with exceptional precision and reliability. Manufactured in CHINA and certified with CE, this advanced rework station features an optical alignment system that ensures accurate placement and efficient rework processes.

With a maximum BGA size of 80x80mm and PCB thickness ranging from 0.3 to 5mm, the WDS620 provides versatile handling suitable for various repair tasks. Its placement accuracy of ±0.01mm guarantees precise component positioning, making it ideal for delicate motherboard repair jobs.

Powered by 220V/110V and supporting a maximum mounting load of 300g, this station balances power and delicacy. The unit comes securely packaged in a wooden case, ensuring safe delivery within 3-5 days after order confirmation.

WDS offers a minimum order quantity of just 1 unit, backed by a supply ability of 200 units, and flexible payment terms via TT. Choose the WDS620 Semi Automatic BGA Rework Station for a reliable, high-precision optical alignment system to enhance your motherboard repair operations.

Support and Services:

The Semi Automatic BGA Rework Station is designed to provide precise and efficient soldering and desoldering of Ball Grid Array (BGA) components. It features advanced temperature control, ensuring uniform heat distribution to prevent damage to sensitive electronic parts during the rework process.

This station supports a wide range of BGA packages and is equipped with an easy-to-use interface, allowing operators to set and monitor

reflow profiles accurately. The semi-automatic functionality streamlines the rework procedure, improving productivity and consistency.
Our technical support team offers comprehensive assistance, including setup guidance, troubleshooting, and maintenance advice to help you maximize the performance and lifespan of your BGA rework station. Replacement parts and firmware updates are available to keep your equipment operating at peak efficiency.
Additionally, we provide training services and detailed user manuals to ensure you and your team can operate the Semi Automatic BGA Rework Station safely and effectively.

Packing and Shipping:

Product Packaging:
The Semi Automatic BGA Rework Station is carefully packaged to ensure safe delivery and protection during transit. It is packed in a sturdy, high-quality cardboard box with custom foam inserts to prevent any movement or damage. The packaging includes all necessary accessories, user manuals, and warranty cards securely placed within the box. The outer box is clearly labeled with product information and handling instructions.
Shipping:
We offer reliable shipping options to deliver the Semi Automatic BGA Rework Station promptly and safely to your location. The product is shipped via trusted courier services with tracking information provided to the customer. Shipping times vary depending on the destination but typically range from 3 to 10 business days. International shipping is available with appropriate customs documentation included. Special care is taken to handle the package as fragile to avoid any damage during transport.

FAQ:

Q1: What is the brand and model number of this Semi Automatic BGA Rework Station?
A1: The brand name is WDS and the model number is WDS620.
Q2: Where is the WDS620 Semi Automatic BGA Rework Station manufactured?
A2: It is made in CHINA.
Q3: Does the WDS620 have any quality certifications?
A3: Yes, the product is CE certified.
Q4: What is the minimum order quantity for this product?
A4: The minimum order quantity is 1 unit.
Q5: How is the WDS620 Semi Automatic BGA Rework Station packaged for delivery?
A5: It is packaged in a sturdy wooden case to ensure safe shipment.
Q6: What is the typical delivery time after placing an order?
A6: The delivery time is usually between 3-5 days.
Q7: What are the accepted payment terms for purchasing the WDS620?
A7: Payment is accepted via TT (Telegraphic Transfer).
Q8: What is the supply ability for this product?
A8: The supply ability is 200 units.

Shenzhen Wisdomshow Technology Co.,ltd

☎ +86 18926538696 ✉ elysia.li@wdsbga.cn bgaxraymachine.com

No.6,Haosi Western Industry,Shangjing Town,Bao'an District,Shenzhen,China